✓**RoHS**

RF Power Field Effect Transistors
N-Channel Enhancement-Mode Lateral MOSFETs

Designed for PCN and PCS base station applications with frequencies from 1930 to 1990 MHz. Suitable for TDMA, CDMA and multicarrier amplifier applications. To be used in Class AB for PCN-PCS/cellular radio and WLL applications.

- Typical 2-Carrier N-CDMA Performance: V_{DD} = 28 Volts, I_{DQ} = 1150 mA, P_{out} = 29 Watts Avg., Full Frequency Band, IS-95 CDMA (Pilot, Sync, Paging, Traffic Codes 8 Through 13) Channel Bandwidth = 1.2288 MHz, PAR = 9.8 dB @ 0.01% Probability on CCDF.
  Power Gain — 16 dB
  Drain Efficiency — 27.5%
  IM3 @ 2.5 MHz Offset — -37 dBc in 1.2288 MHz Channel Bandwidth
  ACPR @ 885 kHz Offset — -51 dBc in 30 kHz Channel Bandwidth
- Capable of Handling 10:1 VSWR, @ 28 Vdc, 1960 MHz, 140 Watts CW Output Power

Features
- Characterized with Series Equivalent Large-Signal Impedance Parameters
- Internally Matched for Ease of Use
- Qualified Up to a Maximum of 32 V_{DD} Operation
- Integrated ESD Protection
- Optimized for Doherty Applications
- RoHS Compliant
- In Tape and Reel. R3 Suffix = 250 Units per 56 mm, 13 inch Reel.

MRF6S19140HR3
MRF6S19140HSR3

**1930-1990 MHz, 29 W AVG., 28 V
2 x N-CDMA
LATERAL N-CHANNEL
RF POWER MOSFETs**

CASE 465B-03, STYLE 1
NI-880
MRF6S19140HR3

CASE 465C-02, STYLE 1
NI-880S
MRF6S19140HSR3
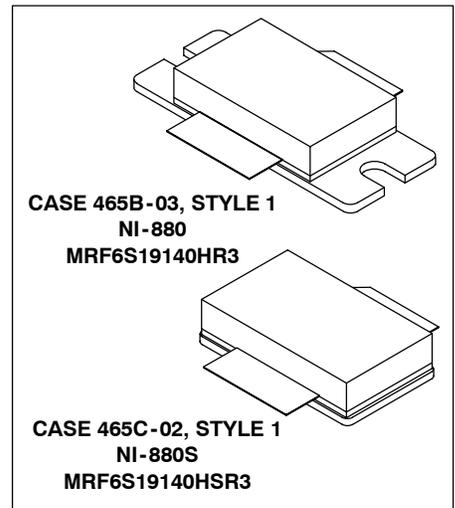
Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	-0.5, +68	Vdc
Gate-Source Voltage	V_{GS}	-0.5, +12	Vdc
Storage Temperature Range	T_{stg}	-65 to +150	°C
Case Operating Temperature	T_C	150	°C
Operating Junction Temperature [1,2]	T_J	225	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value [2,3]	Unit

Thermal Resistance, Junction to Case
    Case Temperature 80°C, 140 W CW
    Case Temperature 77°C, 29 W CW
	$R_{\theta JC}$	
		0.33
		0.38
			°C/W

1. Continuous use at maximum temperature will affect MTTF.
2. MTTF calculator available at http://www.freescale.com/rf. Select Tools/Software/Application Software/Calculators to access the MTTF calculators by product.
3. Refer to AN1955, *Thermal Measurement Methodology of RF Power Amplifiers.* Go to http://www.freescale.com/rf. Select Documentation/Application Notes - AN1955.

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Table 3. ESD Protection Characteristics

| Test Methodology	Class
Human Body Model (per JESD22-A114)	2 (Minimum)
Machine Model (per EIA/JESD22-A115)	A (Minimum)
Charge Device Model (per JESD22-C101)	IV (Minimum)

Table 4. Electrical Characteristics (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Off Characteristics					
Zero Gate Voltage Drain Leakage Current (V_{DS} = 68 Vdc, V_{GS} = 0 Vdc)	I_{DSS}	—	—	10	µAdc
Zero Gate Voltage Drain Leakage Current (V_{DS} = 28 Vdc, V_{GS} = 0 Vdc)	I_{DSS}	—	—	1	µAdc
Gate-Source Leakage Current (V_{GS} = 5 Vdc, V_{DS} = 0 Vdc)	I_{GSS}	—	—	1	µAdc
On Characteristics					
Gate Threshold Voltage (V_{DS} = 10 Vdc, I_D = 300 µAdc)	$V_{GS(th)}$	1	2	3	Vdc
Gate Quiescent Voltage (V_{DD} = 28 Vdc, I_D = 1150 mAdc, Measured in Functional Test)	$V_{GS(Q)}$	2	2.8	4	Vdc
Drain-Source On-Voltage (V_{GS} = 10 Vdc, I_D = 3 Adc)	$V_{DS(on)}$	0.1	0.21	0.3	Vdc
Dynamic Characteristics [1]					
Reverse Transfer Capacitance (V_{DS} = 28 Vdc ± 30 mV(rms)ac @ 1 MHz, V_{GS} = 0 Vdc)	C_{rss}	—	2	—	pF

Functional Tests (In Freescale Test Fixture, 50 ohm system) V_{DD} = 28 Vdc, I_{DQ} = 1150 mA, P_{out} = 29 W Avg., f1 = 1930 MHz, f2 = 1932.5 MHz and f1 = 1987.5 MHz, f2 = 1990 MHz, 2-carrier N-CDMA, 1.2288 MHz Channel Bandwidth Carriers. ACPR measured in 30 kHz Channel Bandwidth @ ±885 kHz Offset. IM3 measured in 1.2288 MHz Channel Bandwidth @ ±2.5 MHz Offset. PAR = 9.8 dB @ 0.01% Probability on CCDF.

	Symbol	Min	Typ	Max	Unit
Power Gain	G_{ps}	15	16	18	dB
Drain Efficiency	η_D	26	27.5	—	%
Intermodulation Distortion	IM3	—	-37	-35	dBc
Adjacent Channel Power Ratio	ACPR	—	-51	-48	dBc
Input Return Loss	IRL	—	-15	-9	dB

1. Part is internally matched both on input and output.

Figure 1. MRF6S19140HR3(HSR3) Test Circuit Schematic
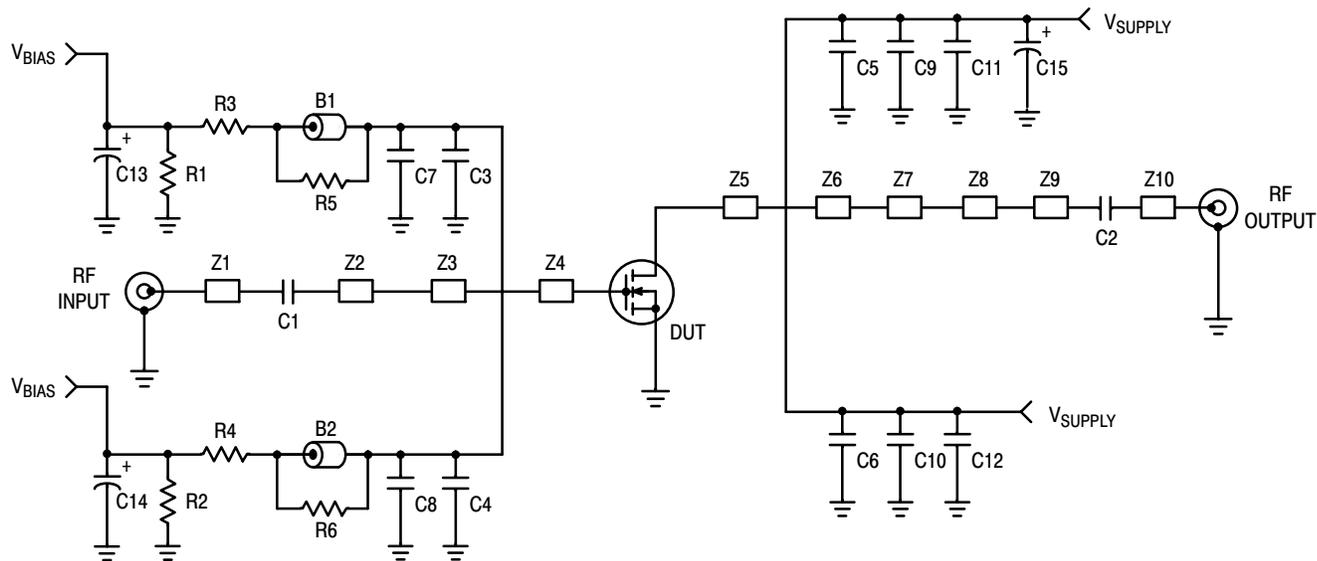
Z1	0.864″ x 0.082″ Microstrip		Z7	0.115″ x 0.569″ Microstrip
Z2	1.373″ x 0.082″ Microstrip		Z8	0.191″ x 0.289″ Microstrip
Z3	0.282″ x 0.900″ Microstrip		Z9	0.681″ x 0.081″ Microstrip
Z4	0.103″ x 0.900″ Microstrip		Z10	1.140″ x 0.081″ Microstrip
Z5	0.094″ x 1.055″ Microstrip		PCB	Arlon GX0300-55-22, 0.030″, ε_r = 2.5
Z6	0.399″ x 1.055″ Microstrip			

Table 5. MRF6S19140HR3(HSR3) Test Circuit Component Designations and Values

Part	Description	Part Number	Manufacturer
B1, B2	Beads, Surface Mount	2743019447	Fair-Rite
C1, C2	39 pF Chip Capacitors	ATC100B390JT500XT	ATC
C3, C4, C5, C6	9.1 pF Chip Capacitors	ATC100B9R1CT500XT	ATC
C7, C8, C9, C10, C11, C12	10 µF, 50 V Chip Capacitors	GRM55DR61H106KA88B	Murata
C13, C14	47 µF, 50 V Electrolytic Capacitors	EMVY500ADA470MF80G	Nippon
C15	470 µF, 63 V Electrolytic Capacitor	ESMG630ELL471MK205	United Chemi-Con
R1, R2	560 kΩ, 1/4 W Chip Resistors	CRCW12065600FKTA	Vishay
R3, R4	1.0 kΩ, 1/4 W Chip Resistors	CRCW12061001FKTA	Vishay
R5, R6	12 Ω, 1/4 W Chip Resistors	CRCW120612R0FKTA	Vishay
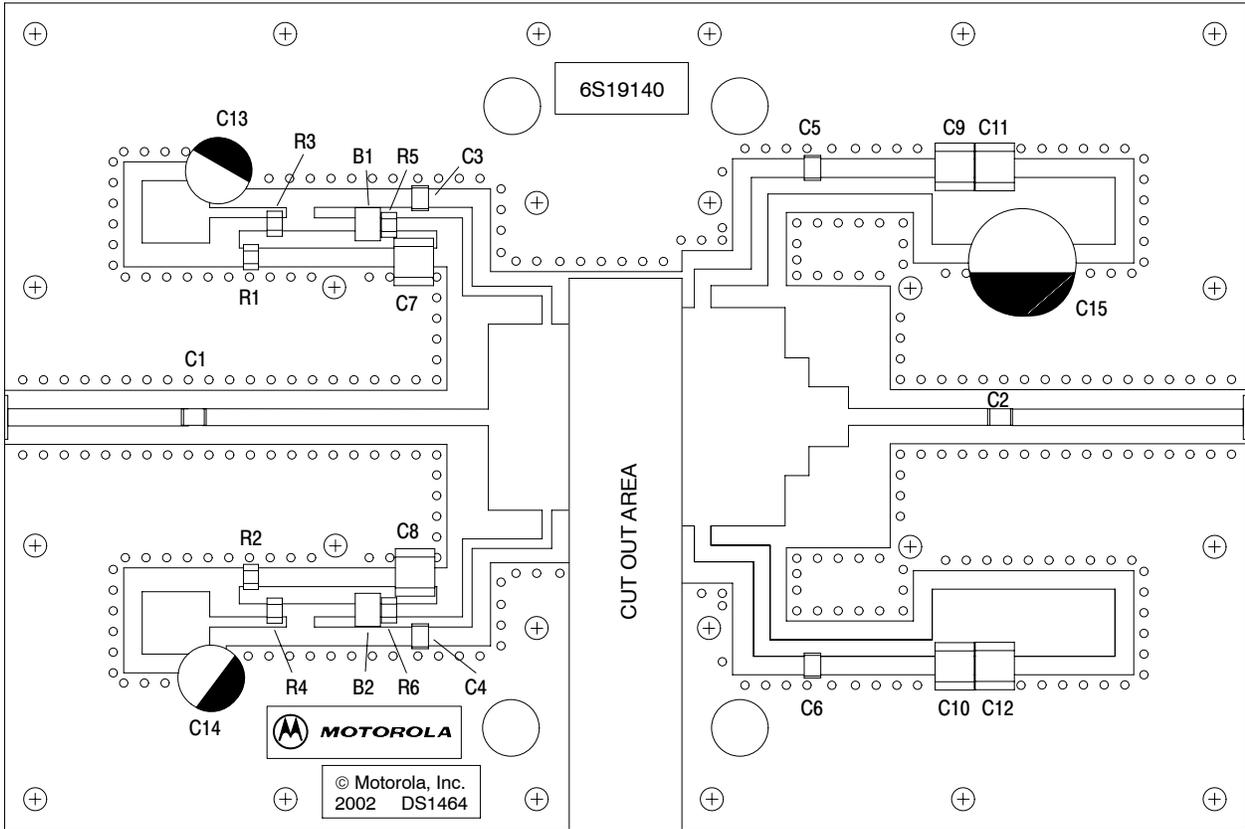
Freescale has begun the transition of marking Printed Circuit Boards (PCBs) with the Freescale Semiconductor signature/logo. PCBs may have either Motorola or Freescale markings during the transition period. These changes will have no impact on form, fit or function of the current product.

**Figure 2. MRF6S19140HR3(HSR3) Test Circuit Component Layout**

TYPICAL CHARACTERISTICS
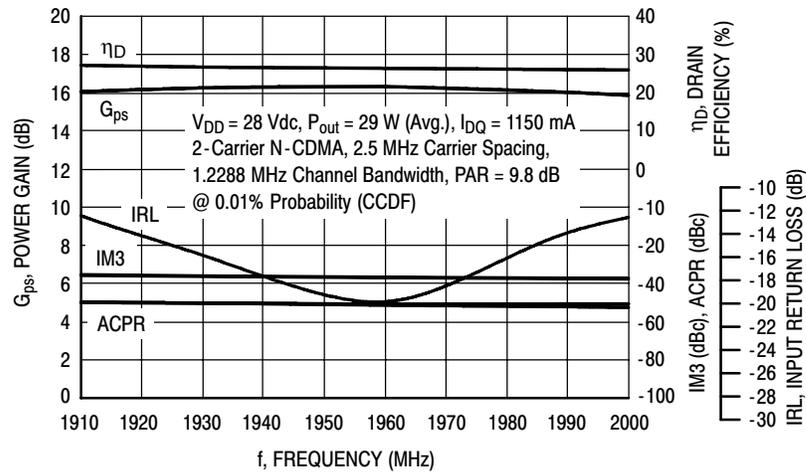
Figure 3. 2-Carrier N-CDMA Broadband Performance @ P_{out} = 29 Watts Avg.
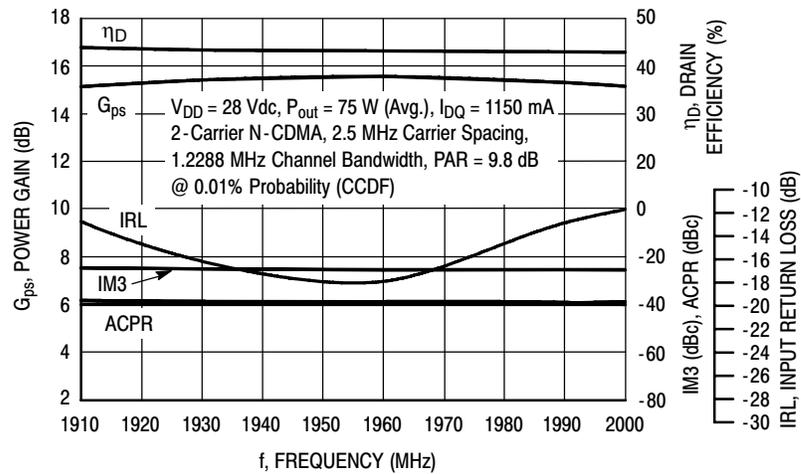
Figure 4. 2-Carrier N-CDMA Broadband Performance @ P_{out} = 75 Watts Avg.
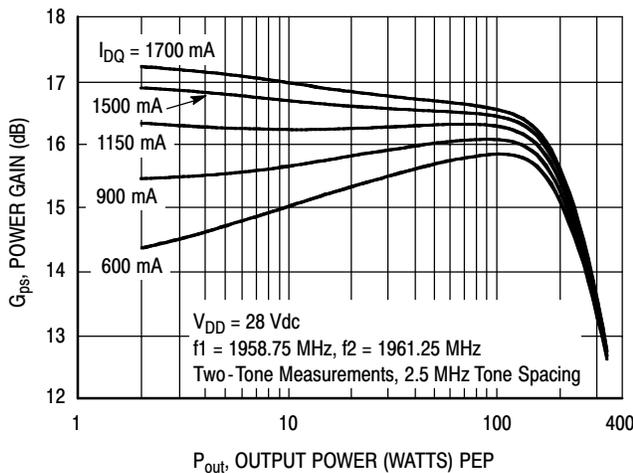
Figure 5. Two-Tone Power Gain versus Output Power
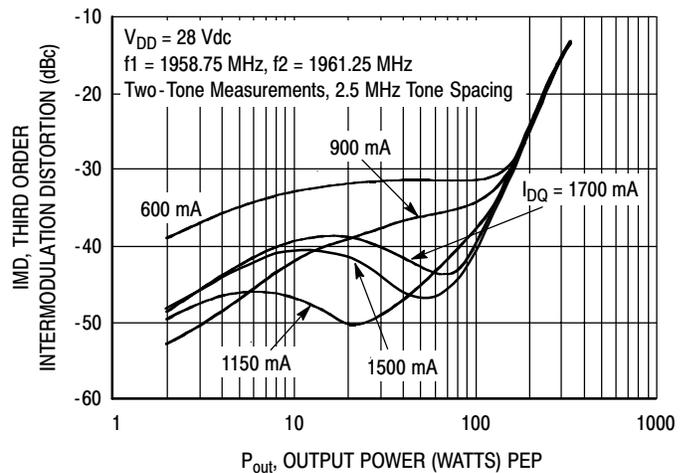
Figure 6. Third Order Intermodulation Distortion versus Output Power

MRF6S19140HR3 MRF6S19140HSR3

TYPICAL CHARACTERISTICS
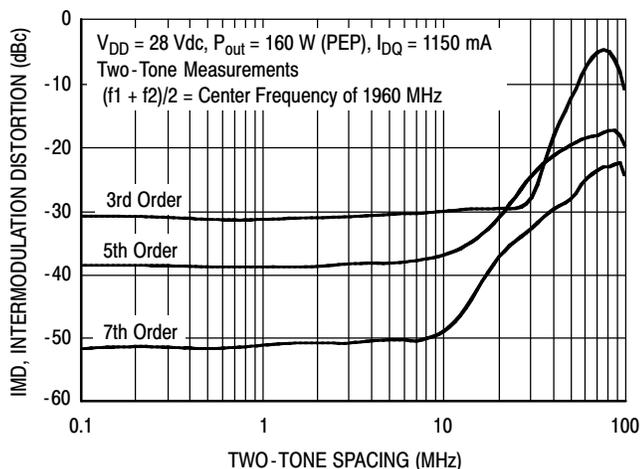
Figure 7. Intermodulation Distortion Products versus Tone Spacing

V_{DD} = 28 Vdc, P_{out} = 160 W (PEP), I_{DQ} = 1150 mA
Two-Tone Measurements
(f1 + f2)/2 = Center Frequency of 1960 MHz

3rd Order
5th Order
7th Order
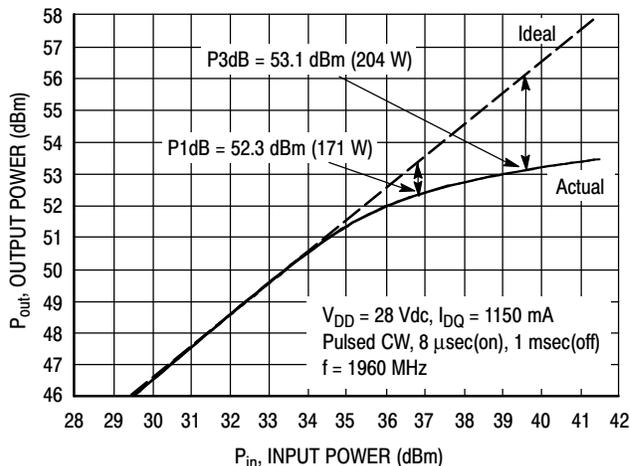
Figure 8. Pulsed CW Output Power versus Input Power

Ideal
P3dB = 53.1 dBm (204 W)
P1dB = 52.3 dBm (171 W)
Actual
V_{DD} = 28 Vdc, I_{DQ} = 1150 mA
Pulsed CW, 8 μsec(on), 1 msec(off)
f = 1960 MHz
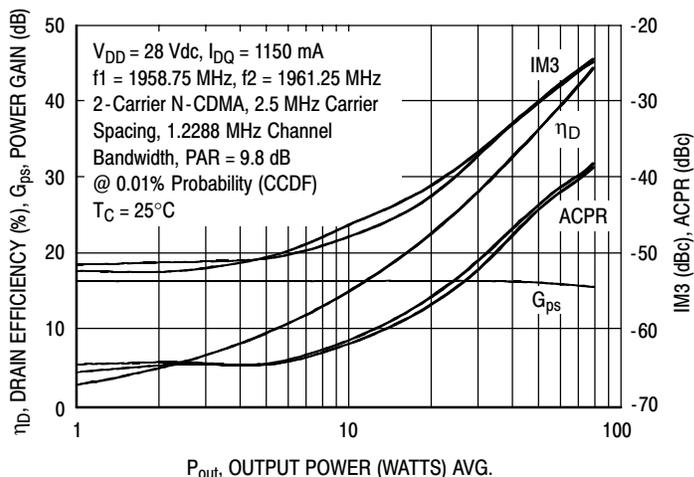
Figure 9. 2-Carrier N-CDMA ACPR, IM3, Power Gain and Drain Efficiency versus Output Power

V_{DD} = 28 Vdc, I_{DQ} = 1150 mA
f1 = 1958.75 MHz, f2 = 1961.25 MHz
2-Carrier N-CDMA, 2.5 MHz Carrier
Spacing, 1.2288 MHz Channel
Bandwidth, PAR = 9.8 dB
@ 0.01% Probability (CCDF)
T_C = 25°C

IM3
η_D
ACPR
G_{ps}
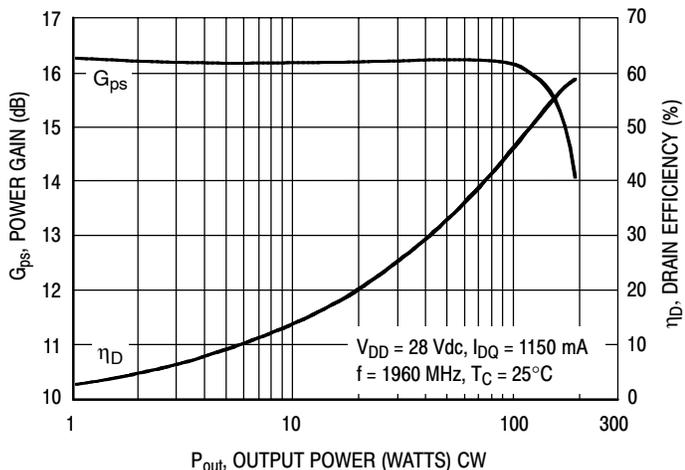
Figure 10. Power Gain and Drain Efficiency versus CW Output Power

G_{ps}
η_D
V_{DD} = 28 Vdc, I_{DQ} = 1150 mA
f = 1960 MHz, T_C = 25°C
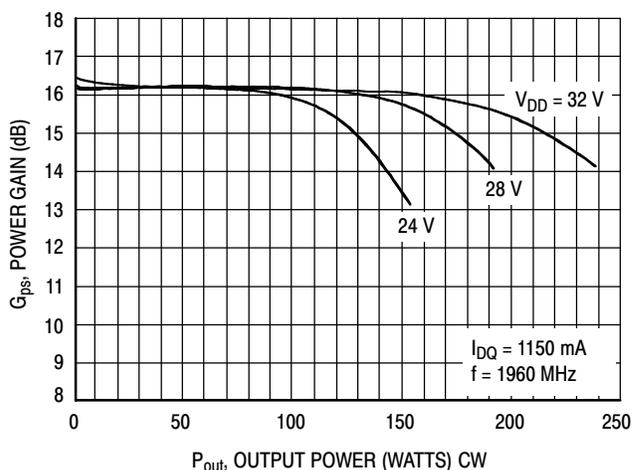
Figure 11. Power Gain versus Output Power

V_{DD} = 32 V
28 V
24 V
I_{DQ} = 1150 mA
f = 1960 MHz

MRF6S19140HR3 MRF6S19140HSR3

TYPICAL CHARACTERISTICS
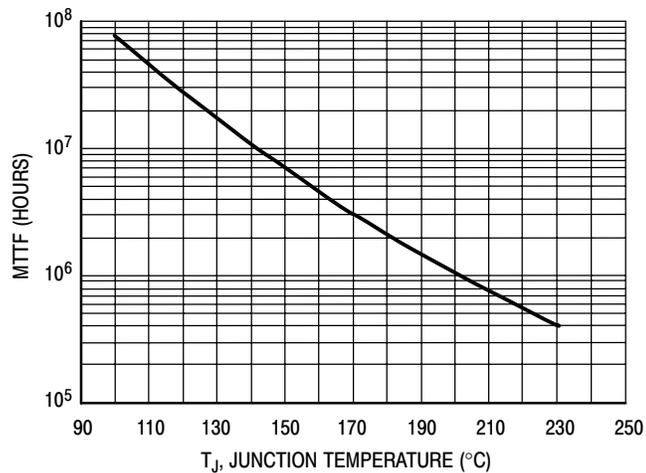
This above graph displays calculated MTTF in hours when the device is operated at V_{DD} = 28 Vdc, P_{out} = 29 W Avg., and η_D = 27.5%.

MTTF calculator available at http://www.freescale.com/rf. Select Tools/Software/Application Software/Calculators to access the MTTF calculators by product.

**Figure 12. MTTF versus Junction Temperature**

N‑CDMA TEST SIGNAL

IS‑95 CDMA (Pilot, Sync, Paging, Traffic Codes 8 Through 13) 1.2288 MHz Channel Bandwidth Carriers. ACPR Measured in 30 kHz Bandwidth @ ±885 kHz Offset. IM3 Measured in 1.2288 MHz Bandwidth @ ±2.5 MHz Offset. PAR = 9.8 dB @ 0.01% Probability on CCDF.
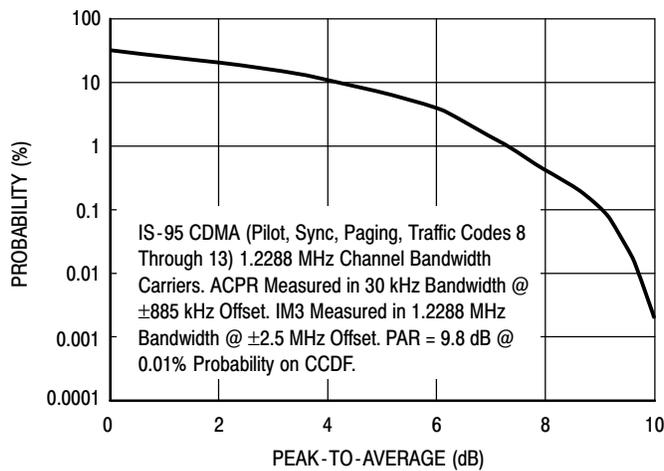
Figure 13. 2‑Carrier CCDF N‑CDMA
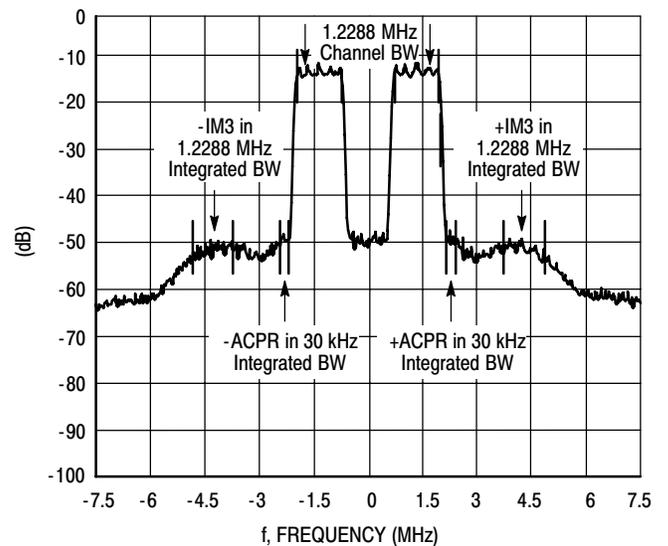
Figure 14. 2‑Carrier N‑CDMA Spectrum
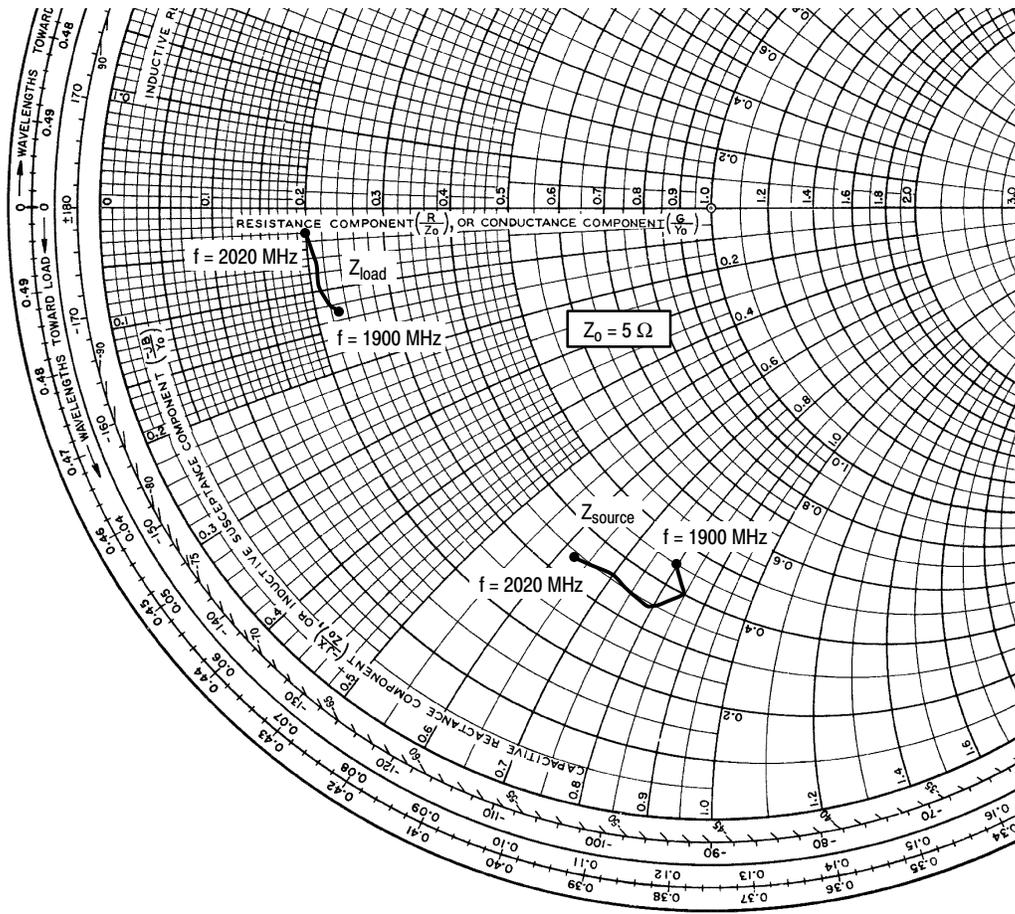
V_{DD} = 28 Vdc, I_{DQ} = 1150 mA, P_{out} = 29 W Avg.

f MHz	Z_{source} Ω	Z_{load} Ω
1900	2.27 - j3.95	1.13 - j0.67
1930	2.00 - j4.24	1.11 - j0.60
1960	1.72 - j3.96	1.07 - j0.46
1990	1.80 - j3.51	1.06 - j0.30
2020	1.69 - j3.17	1.01 - j0.17

Z_{source} = Test circuit impedance as measured from gate to ground.

Z_{load} = Test circuit impedance as measured from drain to ground.
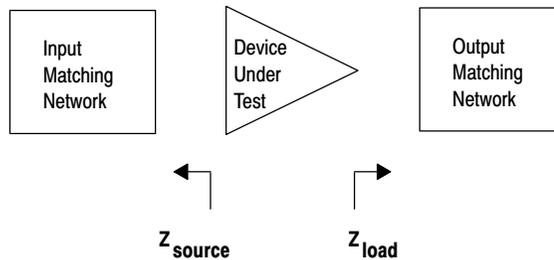
Figure 15. Series Equivalent Source and Load Impedance
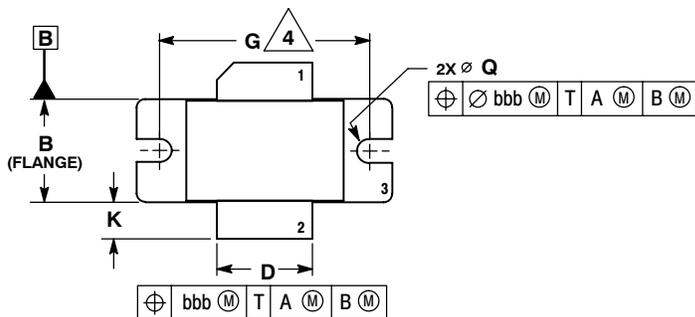
MRF6S19140HR3 MRF6S19140HSR3

PACKAGE DIMENSIONS

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION H IS MEASURED 0.030 (0.762) AWAY FROM PACKAGE BODY.
4. RECOMMENDED BOLT CENTER DIMENSION OF 1.16 (29.57) BASED ON M3 SCREW.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	1.335	1.345	33.91	34.16
B	0.535	0.545	13.6	13.8
C	0.147	0.200	3.73	5.08
D	0.495	0.505	12.57	12.83
E	0.035	0.045	0.89	1.14
F	0.003	0.006	0.08	0.15
G	1.100 BSC		27.94 BSC	
H	0.057	0.067	1.45	1.70
K	0.175	0.205	4.44	5.21
M	0.872	0.888	22.15	22.55
N	0.871	0.889	19.30	22.60
Q	Ø.118	Ø.138	Ø3.00	Ø3.51
R	0.515	0.525	13.10	13.30
S	0.515	0.525	13.10	13.30
aaa	0.007 REF		0.178 REF	
bbb	0.010 REF		0.254 REF	
ccc	0.015 REF		0.381 REF	

STYLE 1:
PIN 1. DRAIN
     2. GATE
     3. SOURCE
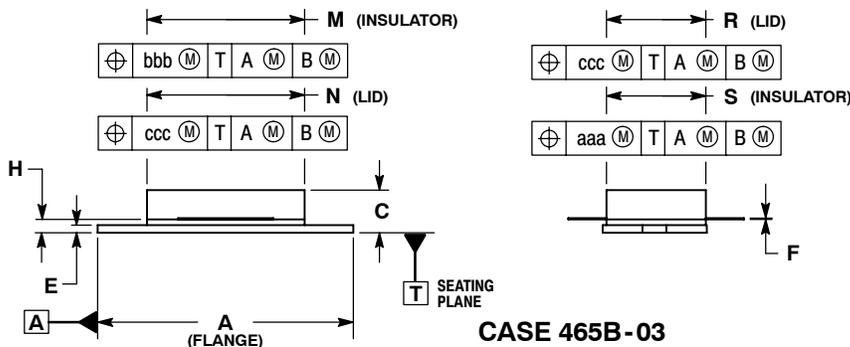
CASE 465B-03
ISSUE D
NI-880
MRF6S19140HR3
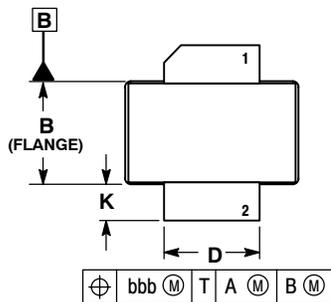
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION H IS MEASURED 0.030 (0.762) AWAY FROM PACKAGE BODY.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.905	0.915	22.99	23.24
B	0.535	0.545	13.60	13.80
C	0.147	0.200	3.73	5.08
D	0.495	0.505	12.57	12.83
E	0.035	0.045	0.89	1.14
F	0.003	0.006	0.08	0.15
H	0.057	0.067	1.45	1.70
K	0.170	0.210	4.32	5.33
M	0.872	0.888	22.15	22.55
N	0.871	0.889	19.30	22.60
R	0.515	0.525	13.10	13.30
S	0.515	0.525	13.10	13.30
aaa	0.007 REF		0.178 REF	
bbb	0.010 REF		0.254 REF	
ccc	0.015 REF		0.381 REF	

STYLE 1:
PIN 1. DRAIN
     2. GATE
     3. SOURCE
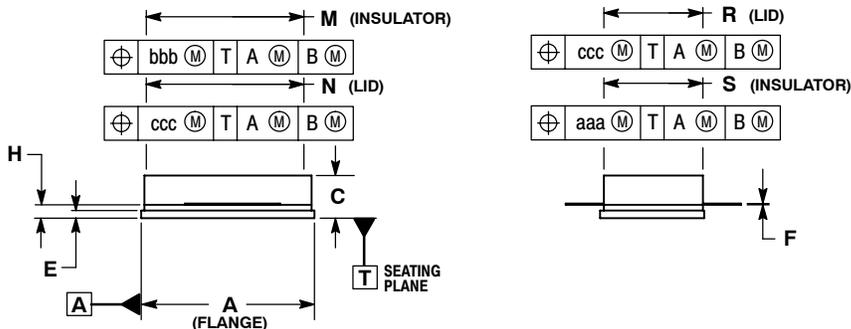
CASE 465C-02
ISSUE D
NI-880S
MRF6S19140HSR3

PRODUCT DOCUMENTATION

Refer to the following documents to aid your design process.

Application Notes

- AN1955: Thermal Measurement Methodology of RF Power Amplifiers

Engineering Bulletins

- EB212: Using Data Sheet Impedances for RF LDMOS Devices

REVISION HISTORY

The following table summarizes revisions to this document.

Revision	Date	Description
5	May 2007	• Removed Lower Thermal Resistance and Low Gold Plating bullets from Features section as functionality is standard, p. 1
		• Removed "Designed for Lower Memory Effects and Wide Instantaneous Bandwidth Applications" bullet as functionality is standard, p. 1
		• Added "Optimized for Doherty Applications" bullet to Features section, p. 1
		• Removed Total Device Dissipation from Max Ratings table as data was redundant (information already provided in Thermal Characteristics table), p. 1
		• Operating Junction Temperature increased from 200°C to 225°C in Maximum Ratings table and related "Continuous use at maximum temperature will affect MTTF" footnote added, p. 1
		• Corrected V_{DS} to V_{DD} in the RF test condition voltage callout for $V_{GS(Q)}$ and added "Measured in Functional Test", On Characteristics table, p. 2
		• Removed Forward Transconductance from On Characteristics table as it no longer provided usable information, p. 2
		• Updated Part Numbers in Table 5, Component Designations and Values, to RoHS compliant part numbers, p. 3
		• Removed lower voltage tests from Fig. 11, Power Gain versus Output Power, due to fixed tuned fixture limitations, p. 6
		• Replaced Fig. 12, MTTF versus Junction Temperature with updated graph. Removed Amps^2 and listed operating characteristics and location of MTTF calculator for device, p. 7
		• Added Product Documentation and Revision History, p. 10

MRF6S19140HR3 MRF6S19140HSR3

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